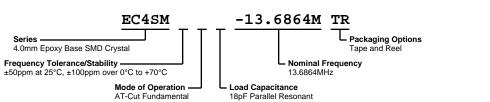
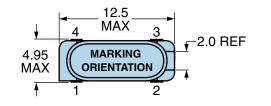
EC4SM-13.6864M TR

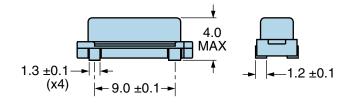


a at 25°C, ±100ppm over 0°C to +70°C year Maximum arallel Resonant ximum
arallel Resonant ximum
ximum
•• •
is Maximum
Fundamental
s Maximum
o +85°C
gaohms Minimum at 100Vdc

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A

MECHANICAL DIMENSIONS (all dimensions in millimeters)





CONNECTION
Connected to Pin 4 and to Crystal
Connected to Pin 3 and to Crystal
Connected to Pin 2 and to Crystal
Connected to Pin 1 and to Crystal
MARKING
E13.686
E=Ecliptek Designator

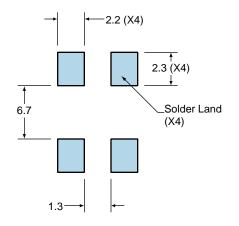


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Suggested Solder Pad Layout

All Dimensions in Millimeters



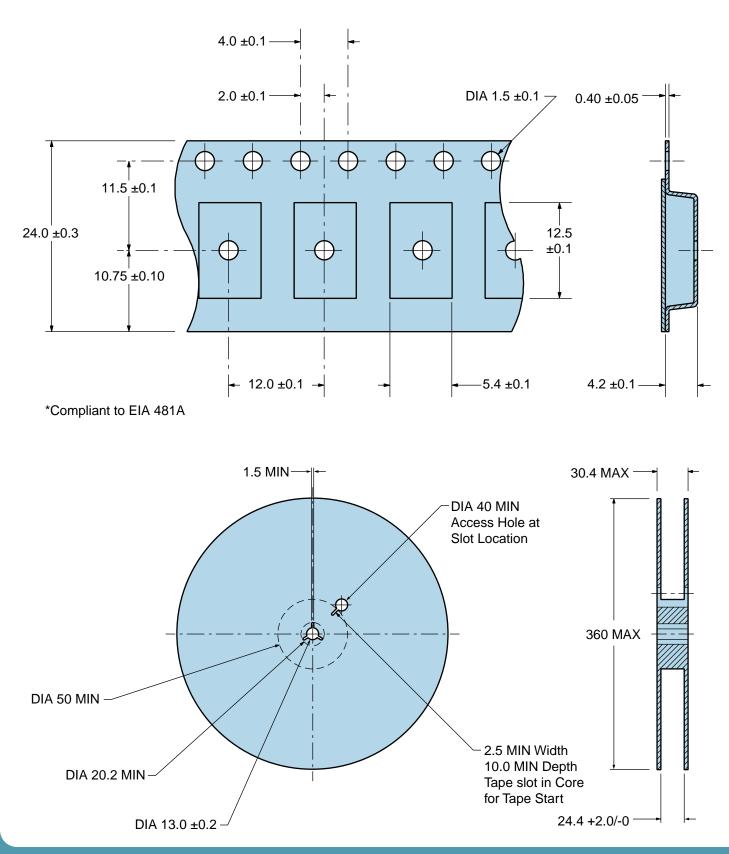
All Tolerances are ±0.1

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Tape & Reel Dimensions

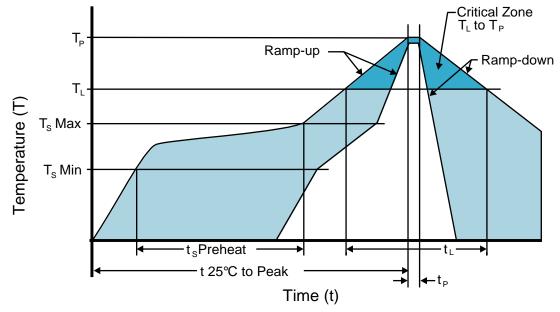
Quantity Per Reel: 1,000 units





Recommended Solder Reflow Methods

EC4SM-13.6864M TR



Low Temperature Infrared/Convection 225°C

T _s MAX to T _L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T⊾ to T _P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T _P)	225°C Maximum
Target Peak Temperature (T _P Target)	225°C Maximum 2 Times
Time within 5°C of actual peak (t _p)	80 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.